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CMOSIC 8K-byte FROM and 256-byte RAM integrated

8-bit 1-chip Microcontroller



http://onsemi.com

Overview

The LC87F2G08A is an 8-bit microcomputer that, integrates on a single chip a number of hardware features such as 8K-byte flash ROM, 256-byte RAM, an On-chip-debugger, a 16-bit timers/counters, two 8-bit timers, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface, an asynchronous/synchronous SIO interface, a UART interface, a 12-bit/8-bit 8-channel AD converter, a system clock frequency divider, an internal reset and an interrupt feature.

Features

- ■Flash ROM
 - 8192×8 bits
 - Capable of On-board programming with wide range (2.2 to 5.5V) of voltage source.
 - Block-erasable in 128 byte units
 - Writable in 2-byte units

■RAM

• 256×9 bits

■Package Form

• MFP24SJ (300mil): Lead-/Halogen-free type

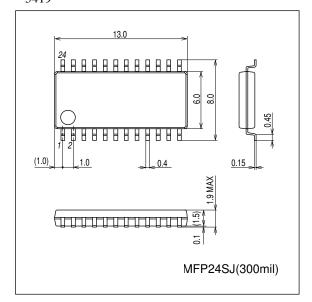
• SSOP24 (225mil): Lead-free type

• VCT24 (3.5×3.5): Lead-/Halogen-free type (build-to-order)

• MFP24S (300mil): Lead-free type (discontinued)

Package Dimensions

unit: mm (typ) 3419

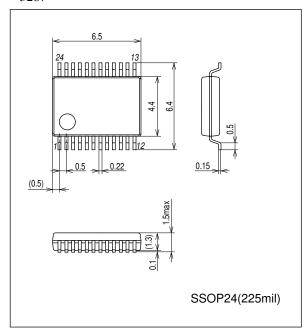


* This product is licensed from Silicon Storage Technology, Inc. (USA).

Package Dimensions

unit: mm (typ)

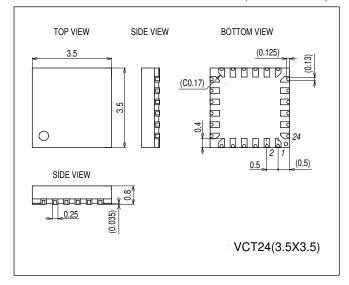
3287



Package Dimensions

unit : mm (typ) 3322A

(Build-to-order)

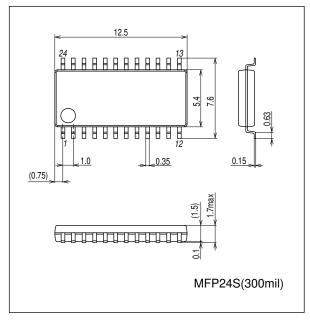


Package Dimensions

unit: mm (typ)

3112B

(Discontinued)



■Minimum Bus Cycle

- 83.3ns (12MHz at V_{DD}=2.7V to 5.5V)
- 100ns (10MHz at V_{DD}=2.2V to 5.5V)
- 250ns (4MHz at V_{DD}=1.8V to 5.5V)

Note: The bus cycle time here refers to the ROM read speed.

■Minimum Instruction Cycle Time

- 250ns (12MHz at V_{DD}=2.7V to 5.5V)
- 300ns (10MHz at V_{DD}=2.2V to 5.5V)
- 750ns (4MHz at V_{DD}=1.8V to 5.5V)

■Ports

• Normal withstand voltage I/O ports

Ports I/O direction can be designated in 1-bit units
11 (P1n, P20, P21, P70)
Ports I/O direction can be designated in 4-bit units
8 (P0n)

• Dedicated oscillator ports/input ports 2 (CF1/XT1, CF2/XT2)

• Reset pin 1 (RES)

• Power pins 2 (V_{SS}1, V_{DD}1)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) \times 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)

+ 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/

counter with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from the lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)

(The lower-order 8 bits can be used as PWM)

- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts are programmable in 5 different time schemes

■High-Speed Clock Counter

- Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
- Can generate output real time.

■SIO

- SIO0: 8-bit Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle=4/3tCYC)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■UART

- Full Duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2 bits in continuous data transmission)
- Built-in baudrate generator
- ■AD Converter: 12 bits/8 bits × 8 channels
 - 12 bits/8 bits AD converter resolution selectable
- ■Remote Control Receiver Circuit (sharing pins with P15, SCK1, INT3, and T0IN)
 - Noise rejection function (noise filter time constant selectable from 1 tCYC, 32 tCYC, and 128 tCYC)

■Clock Output Function

- Can generate clock outputs with a frequency of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 of the source clock selected as the system clock.
- Can generate the source clock for the subclock

■Watchdog Timer

- External RC watchdog timer
- Interrupt and reset signals selectable

■Interrupts

- 18 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3/base timer
5	00023H	H or L	ТОН
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- ■Subroutine Stack Levels: 128levels (The stack is allocated in RAM.)
- High-speed Multiplication/Division Instructions

16 bits × 8 bits (5 tCYC execution time)
24 bits × 16 bits (12 tCYC execution time)
16 bits ÷ 8 bits (8 tCYC execution time)
24 bits ÷ 16 bits (12 tCYC execution time)

■Oscillation Circuits

• Internal oscillation circuits

Low-speed RC oscillation circuit : For system clock (100kHz)
Medium-speed RC oscillation circuit : For system clock (1MHz)
Multifrequency RC oscillation circuit : For system clock (8MHz)

• External oscillation circuits

Hi-speed CF oscillation circuit: For system clock, with internal Rf

Low speed crystal oscillation circuit: For low-speed system clock, with internal Rf

- 1) The CF and crystal oscillation circuits share the same pins. The active circuit is selected under program control.
- 2) Both the CF and crystal oscillator circuits stop operation on a system reset. When the reset is released, only the CF oscillation circuit resumes operation.

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

■Internal Reset Function

- Power-on reset (POR) function
 - 1) POR reset is generated only at power-on time.
 - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
- Low-voltage detection reset (LVD) function
 - 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - 2) The use/disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, 4.28V).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, and crystal oscillators automatically stop operation.
 - 2) There are four ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4
 - * INTO and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0.
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The CF and RC oscillators automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are five ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level.
 - (2) System resetting by watchdog timer or low-voltage detection.
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4
 - * INTO and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0.
 - (5) Having an interrupt source established in the base timer circuit.

Note: Available only when X'tal oscillation is selected.

■Onchip Debugger

- Supports software debugging with the IC mounted on the target board.
- Two channels of on-chip debugger pins are available to be compatible with small pin count devices. DBGP0 (P0), DBGP1 (P1)
- ■Data Security Function (flash versions only)
 - Protects the program data stored in flash memory from unauthorized read or copy.

Note: This data security function does not necessarily provide absolute data security.

■Development Tools

- On-chip debugger: (1) TCB87 type B + LC87D2G08A
 - (2) TCB87 TypeB + LC87F2G08A
 - (3) TCB87 TypeC (3 wire version) + LC87D2G08A
 - (4) TCB87 TypeC (3 wire version) + LC87F2G08A

Note: LC87F2G08A has an On-chip debugger but its function is limited.

■Flash ROM Programming Boards

Package	Programming boards
MFP24S(300mil)	W87F2GM
MFP24SJ(300mil)	W87F2GMJ
SSOP24(225mil)	W87F2GS
VCT24(3.5×3.5)	(build-to-order)

■Flash ROM Programmer

Maker		Model	Supported version	Device
	Single Programmer	AF9708 AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 02.72 or later	LC87F2H08A
Flash Support Group, Inc. (FSG)	Gang	AF9723/AF9723B(Main body) (Including Ando Electric Co., Ltd. models)	-	-
	Programmer	AF9833(Unit) (Including Ando Electric Co., Ltd. models)	-	-
Flash Support Group, Inc. (FSG)	In-circuit	AF9101/AF9103(Main body) (FSG models)		
+ Our company (Note 1)	Programmer	SIB87(Inter Face Driver) (Our company model)	(Note 2)	LC87F2G08A
Our company	Single/Gang Programmer	SKK/SKK Type B (SanyoFWS)	Application Version 1.04 or later	LC87F2G08A
Our company	In-circuit/Gang Programmer	SKK-DBG Type B (SanyoFWS)	Chip Data Version 2.10 or later	LC6/F2G08A

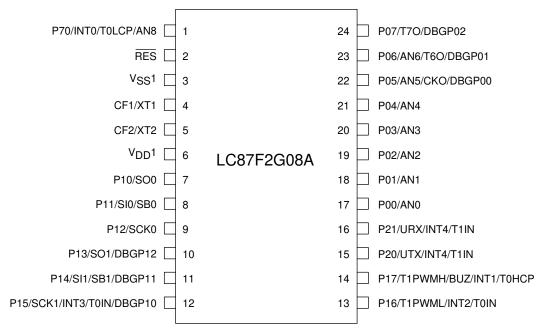
For information about AF-Series:

Flash Support Group, Inc. TEL: +81-53-459-1050 E-mail: sales@j-fsg.co.jp

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together can give a PC-less, standalone on-board-programming capabilities.

Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.

Pin Assignment

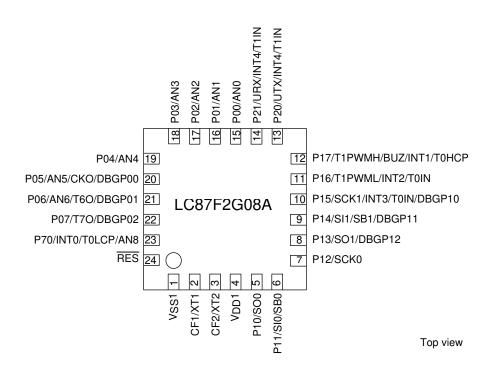


Top view

MFP24S (300mil) "Lead-free Type" MFP24SJ (300mil) "Lead-/Halogen-free Type" SSOP24 (225mil) "Lead-free Type"

MFP24S/	
MFP24SJ/	NAME
SSOP24	
1	P70/INT0/T0LCP/AN8
2	RES
3	V _{SS} 1
4	CF1/XT1
5	CF2/XT2
6	V _{DD} 1
7	P10/SO0
8	P11/SI0/SB0
9	P12/SCK0
10	P13/SO1/DBGP12
11	P14/SI1/SB1/DBGP11
12	P15/SCK1/INT3/T0IN/DBGP10

MFP24S/	
MFP24SJ/	NAME
SSOP24	
13	P16/T1PWML/INT2/T0IN
14	P17/T1PWMH/BUZ/INT1/T0HCP
15	P20/UTX/INT4/T1IN
16	P21/URX/INT4/T1IN
17	P00/AN0
18	P01/AN1
19	P02/AN2
20	P03/AN3
21	P04/AN4
22	P05/AN5/CKO/DBGP00
23	P06/AN6/T6O/DBGP01
24	P07/T7O/DBGP02

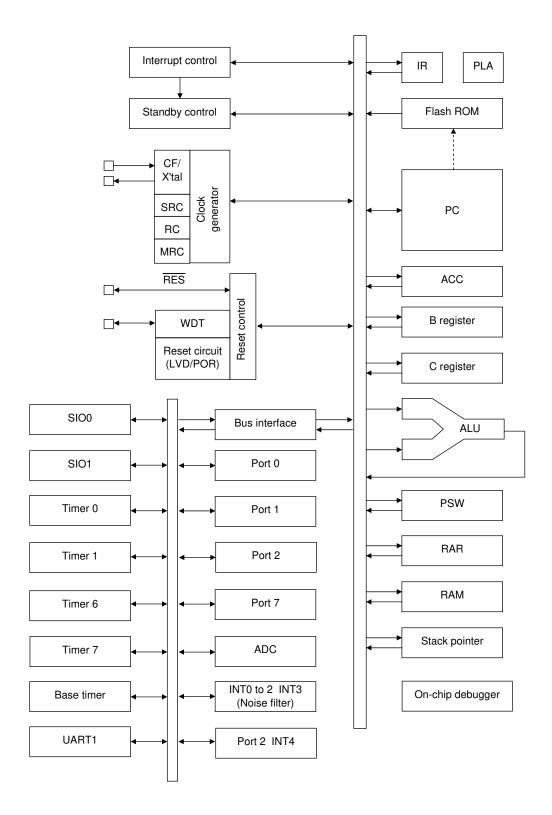


VCT24(3.5×3.5) "Lead-/Halogen-free Type" (build-to-order)

VCT24	NAME	
1	V _{SS} 1	
2	CF1/XT1	
3	CF2/XT2	
4	V _{DD} 1	
5	P10/SO0	
6	P11/SI0/SB0	
7	P12/SCK0	
8	P13/SO1/DBGP12	
9	P14/SI1/SB1/DBGP11	
10	P15/SCK1/INT3/T0IN/DBGP10	
11	P16/T1PWML/INT2/T0IN	
12	P17/T1PWMH/BUZ/INT1/T0HCP	

VCT24	NAME			
13	P20/UTX/INT4/T1IN			
14	P21/URX/INT4/T1IN			
15	P00/AN0			
16	P01/AN1			
17	P02/AN2			
18	P03/AN3			
19	P04/AN4			
20	P05/AN5/CKO/DBGP00			
21	P06/AN6/T6O/DBGP01			
22	P07/T7O/DBGP02			
23	P70/INT0/T0LCP/AN8			
24	RES			

System Block Diagram



Pin Description

Pin Name	I/O			Desc	cription			Option		
V _{SS} 1	-	- Power supply	pin					No		
V _{DD} 1	-	+ Power supply pin						No		
Port 0	I/O	• 8-bit I/O port								
P00 to P07	7	I/O specifiable	e in 4-bit units							
		Pull-up resiste	ors can be turned	on and off in 4-l	oit units.					
		HOLD reset in	nput							
		Port 0 interrup	pt input							
		 Pin functions 						Yes		
		P05: System	clock output							
		P06: Timer 6								
		P07: Timer 7								
			P06(AN6): AD cor	•						
		•) to P07(DBGP02	e): On-chip debu	gger 0 port					
Port 1	I/O	8-bit I/O port								
P10 to P17		I/O specifiable								
		-	ors can be turned	on and off in 1-l	oit units.					
		Pin functions								
		P10: SIO0 da	•							
			ta input/bus I/O							
		P12: SIO0 clo								
		P13: SIO1 da	•							
			P14: SIO1 data input / bus I/O							
		P15: SIO1 clock I/O / INT3 input (with noise filter) / timer 0 event input / timer 0H capture input P16: Timer 1PWML output / INT2 input/HOLD reset input/timer 0 event input / timer 0L capture								
		input	VVIVIL Output / IIV	12 IIIpul/11OLD I	eset input/timer t	event input / ti	mer of capture	Yes		
		The state of the s	PWMH output / be	ener outnut / IN	T1 input / HOLD	reset innut / tim	er 0H canture			
		input	· · · · · · · · · · · · · · · · · · ·	opor output? III	TT IIIpat / TTOED	root input / tim	or orroupturo			
) to P13(DBGP12): On-chip-debu	ager 1 port					
		Interrupt ackn		,,,	99 P					
			Rising	Falling	Rising & Falling	H level	L level			
		INIT4		T		1				
		INT1	enable	enable	disable	enable	enable			
		INT1	enable enable	enable enable	disable enable	enable disable	enable disable			
Port 2	1/0	INT2 INT3	enable	enable	enable	disable	disable			
	I/O	INT2 INT3 • 2-bit I/O port	enable enable	enable	enable	disable	disable			
	1/0	INT2 INT3 • 2-bit I/O port • I/O specifiable	enable enable e in 1-bit units	enable enable	enable enable	disable	disable			
	I/O	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste	enable enable	enable enable	enable enable	disable	disable			
	I/O	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions	enable enable e in 1-bit units ors can be turned	enable enable	enable enable	disable	disable			
	//O	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste	enable enable e in 1-bit units ors can be turned ansmit	enable enable	enable enable	disable	disable			
	1/0	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions P20: UART tr	enable enable e in 1-bit units ors can be turned ansmit	enable enable on and off in 1-I	enable enable	disable disable	disable disable	Yac		
Port 2 P20 to P21	1/0	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions P20: UART tra P21: UART re	enable enable e in 1-bit units ors can be turned ansmit	enable enable on and off in 1-I	enable enable	disable disable	disable disable	Yes		
	1/0	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions P20: UART tra P21: UART re P20 to P21: If	enable enable e in 1-bit units ors can be turned ansmit eceive	enable enable on and off in 1-I	enable enable	disable disable	disable disable	Yes		
	I/O	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions P20: UART tra P21: UART re P20 to P21: If	enable enable e in 1-bit units ors can be turned ansmit eceive NT4 input / HOLD IH capture input owledge types	enable enable on and off in 1-l	enable enable	disable disable	disable disable	Yes		
	I/O	INT2 INT3 • 2-bit I/O port • I/O specifiable • Pull-up resiste • Pin functions P20: UART tra P21: UART re P20 to P21: If	enable enable e in 1-bit units ors can be turned ansmit eceive NT4 input / HOLD iH capture input	enable enable on and off in 1-I	enable enable bit units. er 1 event input /	disable disable	disable disable	Yes		

Continued on next page.

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Pin Name	I/O			Des	cription				Option
Port 7 P70	I/O	1-bit I/O port I/O specifiable Pull-up resistor Pin functions P70: INT0 input P70(AN8): AD of Interrupt acknowledges	s can be turned t / HOLD reset in converter input	on and off in 1-	·	atchdog timer ou H level enable	L level enable		No
RES	I/O	External reset in	out / internal res	et output					No
CF1/XT1	I	Ceramic resonator or 32.768kHz crystal oscillator input pin Pin function General-purpose input port						No	
CF2/XT2	I/O	Ceramic resona Pin function General-purpos		Hz crystal oscilla	tor output pin				No

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable

Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low-and high-impedance pull-up connection is exercised in nibble (4-bit) units (P00 to 03 or P04 to 07).

User Option Table

Option Name	Option to be Applied on	Flash-ROM Version	Option Selected in Units of	Option Selection
	P00 to P07	0	1 bit	CMOS
				Nch-open drain
Dark autout tona	P10 to P17	0	1 bit	CMOS
Port output type				Nch-open drain
	P20 to P21	0	1 bit	CMOS
				Nch-open drain
Program start	-	0	-	00000h
address				01E00h
Low-voltage	Detect function	0	-	Enable:Use
detection reset				Disable:Not Used
function	Detect level	0	•	7-level
Power-on reset function	Power-On reset level	0	-	8-level

Recommended Unused Pin Connections

DestMana	Recommended Unused Pin Connections			
Port Name	Board	Software		
P00 to P07	Open	Output low		
P10 to P17	Open	Output low		
P20 to P21	Open	Output low		
P70	Open	Output low		
CF1/XT1	Pulled low with a 100kΩ resistor or less	General-purpose input port		
CF2/XT2	Pulled low with a 100kΩ resistor or less	General-purpose input port		

Notes on CF1/XT1 and CF2/XT2 pins

• When using as general-purpose input ports Since the CF1/XT1 and CF2/XT2 pins are configured as CF oscillator pins at system reset time, it is necessary to add a current limiting resistor of $1k\Omega$ or greater to the CF2/XT2 pin in series when using them as general-purpose input pins.

• Differences between flash and mask ROM version

		System Reset Time State	After System Reset is Released
FL DOM	CF1/XT1	Set high via the internal Rf resistor	CF oscillation state
Flash ROM version LC87F2G08A	CF2/XT2	Set high	CF oscillation state
Mask ROM version	CF1/XT1	Set low via the internal Rf resistor	CF oscillation state
LC872G08A/06A/04A	CF2/XT2	Set low	CF oscillation state

On-chip Debugger Pin Connection Requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 on-chip debugger installation manual" and "LC872000 series on-chip debugger pin connection requirements"

Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = 0V$

	Parameter	Symbol	Pin/Remarks	Conditions				ication	
		-			V _{DD} [V]	min	typ	max	unit
	ximum supply tage	V _{DD} max	V _{DD} 1			-0.3		+6.5	
	ut voltage	VI	CF1, CF2			-0.3		V _{DD} +0.3	٧
Inp	ut/output	V _{IO}	Ports 0, 1, 2,			-0.3		V _{DD} +0.3	
vol	tage		P70			0.0		10010.0	
ut	Peak output current	IOPH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-10			
High level output current	Mean output current (Note 1-1)	IOMH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-7.5			
vel or	Total output	ΣΙΟΑΗ(1)	P10 to P14	Total of all applicable pins		-20			
High le	current	ΣΙΟΑΗ(2)	Ports 0, 2 P15 to P17	Total of all applicable pins		-20			
		ΣΙΟΑΗ(3)	Ports 0, 1, 2	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				20	
	ourrone	IOPL(2)	P00, P01	Per 1 applicable pin				30	mA
اب		IOPL(3)	P70	Per 1 applicable pin				10	
Low level output current	Mean output current	IOML(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				15	
utbn	(Note 1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	
o lə/		IOML(3)	P70	Per 1 applicable pin				7.5	
w e	Total output	ΣIOAL(1)	P10 to P14	Total of all applicable pins				50	
Lo	current	ΣIOAL(2)	Port 0, 2, P15 to P17	Total of all applicable pins				60	
		ΣIOAL(3)	Ports 0, 1, 2	Total of all applicable pins				70	
		ΣIOAL(4)	P70	Total of all applicable pins				7.5	
	wer sipation	Pd max(1)	MFP24S(300mil)	Ta=-40 to +85°C Package only				129	
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				229	
		Pd max(3)	MFP24SJ(300mil)	Ta=-40 to +85°C Package only				171	
		Pd max(4)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				393	mW
		Pd max(5)	SSOP24(225mil)	Ta=-40 to +85°C Package only				111	
		Pd max(6)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				334	
		Pd max(7)	VCT24(3.5×3.5)	Ta=-40 to +85°C				T.B.D	
		Pd max(8)		Package only Ta=-40 to +85°C Package with thermal resistance board				T.B.D	
	erating ambient	Topr		issistance board		-40		+85	
Sto	orage ambient	Tstg				-55		+125	°C

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: $76.1 \times 114.3 \times 1.6$ tmm, glass epoxy) is used.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

Davamatav	Cumbal	Pin/Remarks	Conditions			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1	0.245μs ≤ tCYC ≤ 200μs		2.7		5.5	
supply voltage	V _{DD} (2)		0.294μs ≤ tCYC ≤ 200μs		2.2		5.5	
(Note 2-1)	V _{DD} (3)		0.735μs ≤ tCYC ≤ 200μs		1.8		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1	RAM and register contents sustained in HOLD mode.		1.6			
High level input voltage	V _{IH} (1)	Ports 1, 2, P70 port input/ interrupt side		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Ports 0		1.8 to 5.5	0.3V _{DD} +0.7		V_{DD}	
	V _{IH} (3)	Port 70 watchdog timer side		1.8 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (4)	CF1, RES		1.8 to 5.5	0.75V _{DD}		V_{DD}	
Low level	V _{IL} (1)	Ports 1, 2,		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
input voltage		P70 port input/ interrupt side		1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (2)	Ports 0		4.0 to 5.5	V_{SS}		0.15V _{DD} +0.4	
				1.8 to 4.0	V_{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 70 watchdog timer side		1.8 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (4)	CF1, RES		1.8 to 5.5	V_{SS}		0.25V _{DD}	
Instruction	tCYC			2.7 to 5.5	0.245		200	
cycle time	(Note 2-2)			2.2 to 5.5	0.294		200	μs
(Note 2-1)				1.8 to 5.5	0.735		200	
External	FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12	
system clock frequency			System clock frequency division ratio=1/1 External system clock duty=50±5%	1.8 to 5.5	0.1		4	
			CF2 pin open	3.0 to 5.5	0.2		24.4	MHz
			System clock frequency division ratio=1/2 External system clock duty=50±5%	2.0 to 5.5	0.2		8	
Oscillation frequency	FmCF(1)	CF1, CF2	12MHz ceramic oscillation. See Fig. 1.	2.7 to 5.5		12		
range (Note 2-3)	FmCF(2)	CF1, CF2	10MHz ceramic oscillation. See Fig. 1.	2.2 to 5.5		10		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation. CF oscillation normal amplifier size selected. (CFLAMP=0) See Fig. 1.	1.8 to 5.5		4		
			4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1.	2.2 to 5.5		4		MHz
	FmMRC		Frequency variable RC oscillation. 1/2 frequency division ration. (RCCTD=0) (Note 2-4)	2.7 to 5.5	7.44	8.0	8.56	
	FmRC		Internal medium-speed RC oscillation	1.8 to 5.5	0.5	1.0	2.0	
	FmSRC		Internal low-speed RC oscillation	1.8 to 5.5	50	100	200]
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	1.8 to 5.5		32.768		kHz

- Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.
- Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.
- Note 2-3: See Tables 1 and 2 for the oscillation constants.
- Note 2-4: When switching the system clock, allow an oscillation stabilization time of 100µs or longer after the multifrequency RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Electrical Characteristics at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, P70, RES	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	1.8 to 5.5			1	
	I _{IH} (2)	CF1	$V_{IN}=V_{DD}$	1.8 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2, P70, RES	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	1.8 to 5.5	-1			μΑ
	I _{IL} (2)	CF1	V _{IN} =V _{SS}	1.8 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)		I _{OH} =-0.35mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.15mA	1.8 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)		I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (3)		I _{OL} =0.8mA	1.8 to 5.5			0.4	٧
	V _{OL} (4)	P70	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (5)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (6)	P00, P01	I _{OL} =25mA	4.5 to 5.5			1.5	
	V _{OL} (7)		I _{OL} =4mA	2.7 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =2mA	1.8 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	- P70	When Port 0 selected low-impedance pull-up.	1.8 to 4.5	18	50	230	kΩ
	Rpu(3)	Port 0	V _{OH} =0.9V _{DD} When Port 0 selected high-impedance pull-up.	1.8 to 5.5	100	210	400	K22
Hysteresis voltage	VHYS(1)	Ports 1, 2, P70,	·	2.7 to 5.5		0.1V _{DD}		.,
	VHYS(2)	RES		1.8 to 2.7		0.07V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	1.8 to 5.5		10		pF

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

		Parameter	O. wash all	Pin/	Conditions			Speci	fication	
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	• See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(1)			1.8 to 5.5	1			10)(0
Serial clock	lnp	High level pulse width	tSCKH(1)				1			tCYC
erial	k	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected		4/3			
S	Output clock	Low level pulse width	tSCKL(2)		• See Fig. 5.	1.8 to 5.5		1/2		tSCK
	Out	High level pulse width	tSCKH(2)					1/2		ISCK
Serial input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of	1.8 to 5.5	0.05			
Seria	Da	ta hold time	thDI(1)		SIOCLK. • See Fig. 5.	1.6 (0 5.5	0.05			
	Input clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-2)				(1/3)tCYC +0.08	
output	ıduı		tdD0(2)		• Synchronous 8-bit mode (Note 4-1-2)	104-55			1tCYC +0.08	μs
Serial	Serial output Output clock Inp		tdD0(3)		(Note 4-1-2)	1.8 to 5.5			(1/3)tCYC +0.08	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		Davamatar	Cumbal	Pin/	Conditions			Spec	ification	
	l	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(3)			1.8 to 5.5	1			
clock	Serial clock	High level pulse width	tSCKH(3)				1			tCYC
Serial	ck	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig. 5.		2			
	Output clock	Low level pulse width	tSCKL(4)			1.8 to 5.5		1/2		tSCK
		High level pulse width	tSCKH(4)					1/2		ISCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK. See Fig. 5.	400.55	0.05			
Serial	Da	ata hold time	thDI(2)			1.8 to 5.5	0.05			
Serial output	Ou	utput delay time	tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.	1.8 to 5.5			(1/3)tCYC +0.08	μs

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Davasastas	Ol	Pin/Remarks	O and it is a se			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width			Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled.	1.8 to 5.5	1			
	tPIH(2) INT3(P15) when noise tPIL(2) filter time constant is 1/1		Interrupt source flag can be set. Event inputs for timer 0 are enabled.	1.8 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P15) when noise filter time constant is 1/32	Interrupt source flag can be set. Event inputs for timer 0 are nabled.	1.8 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P15) when noise filter time constant is 1/128	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	1.8 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	1.8 to 5.5	200			μs

AD Converter Characteristics at $V_{SS}1 = 0V$

<12bits AD Converter Mode/Ta = -40°C to +85°C >

Davastan	Oh al	Disc/Dassassias	Conditions			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		12		bit
Absolute	ET	AN6(P06)	(Note 6-1)	3.0 to 5.5			±16	
accuracy		AN8(P70)	(Note 6-1) • Ta=-10 to +50°C	2.4 to 3.6			±20	LSB
Conversion time	TCAD		See Conversion time calculation	4.0 to 5.5	32		115	
			formulas. (Note 6-2)	3.0 to 5.5	64		115	
			See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C	2.4 to 3.6	410		425	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	V
	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μΑ

<8bits AD Converter Mode/Ta = -40°C to +85°C >

Davastan	Oh!	Dia /Damania	O and this are			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		8		bit
Absolute accuracy	ET	AN6(P06) AN8(P70)	(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion time	TCAD		See Conversion time calculation	4.0 to 5.5	20		90	
			formulas. (Note 6-2)	3.0 to 5.5	40		90	
			See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C	2.4 to 3.6	250		265	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	٧
Analog port	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μΑ

- Note 6-1: The quantization error $(\pm 1/2LSB)$ must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.
- Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time) = $((52/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 8bits AD Converter Mode: TCAD(Conversion time) = $((32/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$

External oscillation	Operating supply voltage range	System division ratio	Cycle time	AD division ratio	AD conversion time (TCAD)		
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD	
CF-12MHz	4.0V to 5.5V	1/1	250ns	1/8	34.8µs	21.5μs	
GF-12MH2	3.0V to 5.5V	1/1	250ns	1/16	69.5µs	42.8µs	
CF-10MHz	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8µs	
CF-TUIVIHZ	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4µs	
CF-4MHz	3.0V to 5.5V	1/1	750ns	1/8	104.5μs	64.5µs	
GF-4IVIHZ	2.4V to 3.6V	1/1	750ns	1/32	416.5μs	256.5μs	

Power-on Reset (POR) Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

						Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
POR release	PORRL		Select from option.	1.67V	1.55	1.67	1.79	
voltage			(Note 7-1)	1.97V	1.85	1.97	2.09	
				2.07V	1.95	2.07	2.19	
				2.37V	2.25	2.37	2.49	
				2.57V	2.45	2.57	2.69	
				2.87V	2.75	2.87	2.99	V
				3.86V	3.73	3.86	3.99	
				4.35V	4.21	4.35	4.49	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 7-2)			0.7	0.95	
Power supply rise time	PORIS		Power supply rise time from 0V to 1.6V.				100	ms

Note7-1: The POR release level can be selected out of 8 levels only when the LVD reset function is disabled.

Note7-2: POR is in an unknown state before transistors start operation.

Low Voltage Detection Reset (LVD) Characteristics at Ta = -40°C to +85°C, $V_{SS}1=0V$

						Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
LVD reset voltage	LVDET		Select from option.	1.91V	1.81	1.91	2.01	
(Note 8-2)			(Note 8-1)	2.01V	1.91	2.01	2.11	
			(Note 8-3) • See Fig. 8.	2.31V	2.21	2.31	2.41	
			• See Fig. 6.	2.51V	2.41	2.51	2.61	V
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD hysteresys	LVHYS			1.91V		55		
width				2.01V		55		
				2.31V		55		
				2.51V		55		mV
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unknown state	LVUKS		• See Fig. 8. (Note 8-4)			0.7	0.95	٧
Low voltage detection minimum width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 9.		0.2			ms

Note8-1: The LVD reset level can be selected out of 7 levels only when the LVD reset function is enabled.

Note8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note8-4: LVD is in an unknown state before transistors start operation.

Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

Parameter	Symbol	Pin/	Conditions			Specif	ication	
i diametei	Зуппоот	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1	FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal low speed and medium speed RC	2.7 to 5.5		7.4	13.0	
(Note 9-1) (Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		4.4	8.1	
	IDDOP(2)		CF1=24MHz external clock System clock set to CF1 side Internal low speed and medium speed RC	3.0 to 5.5		9.7	16.2	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	3.0 to 3.6		5.3	8.7	
	IDDOP(3)		FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal low speed and medium speed RC oscillation stepped.	2.2 to 5.5		6.6	11.9	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 3.6		4.0	7.4	
	IDDOP(4)		FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal low speed and medium speed RC	1.8 to 5.5		2.9	6.5	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	1.8 to 3.6		2.2	4.2	mA
	IDDOP(5)		CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	2.2 to 5.5		1.1	2.5	
			Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.6	1.3	
	IDDOP(6)		FsX'tal=32.768kHz crystal oscillation mode Internal low speed RC oscillation stopped. System clock set to internal medium speed	1.8 to 5.5		0.6	1.7	
			RC oscillation. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.3	0.9	
	IDDOP(7)		FsX'tal=32.768kHz crystal oscillation mode Internal low speed and medium speed RC oscillation stopped.	2.7 to 5.5		5.0	9.1	
			System clock set to 8MHz with frequency variable RC oscillation 1/1 frequency division ratio	2.7 to 3.6		3.6	5.8	
	IDDOP(8)		External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC oscillation.	1.8 to 5.5		75	370	
_			Internal medium speed RC oscillation sopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		46	192	
	IDDOP(9)		External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC oscillation.	5.0		75	176	μΑ
			Internal medium speed RC oscillation stopped. Frequency variable RC oscillation stopped.	3.3		46	115	
			1/1 frequency division ratio Ta=-10 to +50°C	2.5		35	85	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

Continued on next page.

Continued from preceding page.

Parameter	Symbol	Pin/	Conditions			Speci	ification		
	5,	Remarks	33.13110110	V _{DD} [V]	min	typ	max	unit	
Normal mode consumption current	IDDOP(10)	V _{DD} 1	FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal low speed and medium speed RC	1.8 to 5.5		38	139		
(Note 9-1) (Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		15	66		
	IDDOP(11)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	5.0		38	101	μΑ	
			Internal low speed and medium speed RC oscillation stopped.	3.3		15	46		
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio Ta=-10 to +50°C	2.5		9.0	28		
HALT mode consumption current (Note 9-1)	IDDHALT(1)		HALT mode FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal low speed and medium speed RC	2.7 to 5.5		3.1	5.6		
(Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		1.6	2.9		
	IDDHALT(2)		HALT mode CF1=24MHz external clock System clock set to CF1 side Internal low speed and medium speed RC	3.0 to 5.5		4.9	8.6		
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	3.0 to 3.6		2.3	3.8		
	IDDHALT(3)		HALT mode FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side	2.2 to 5.5		2.7	5.3		
			Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.2 to 3.6		1.4	2.6		
	IDDHALT(4)		HALT mode FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal low speed and medium speed RC	1.8 to 5.5		1.4	3.5	mA	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	1.8 to 3.6		0.7	1.3		
	IDDHALT(5)		HALT mode CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	2.2 to 5.5		0.7	1.8		
			Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.3	0.7		
	IDDHALT(6)		HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal low speed RC oscillation stopped. System clock set to internal medium speed	1.8 to 5.5		0.4	1.1		
			RC oscillation Frequency variable RC oscillation stopped. 1/2 frequency division ratio	1.8 to 3.6		0.2	0.5		

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

Continued on next page.

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Continued from		Pin/	Conditions			Specif	fication	
Parameter	Symbol	remarks	Conditions	V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 9-1)	IDDHALT(7)	V _{DD} 1	HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal low speed and medium speed RC oscillation stopped.	2.7 to 5.5		1.8	3.5	mA
(Note 9-2)			System clock set to 8MHz with frequency variable RC oscillation 1/1 frequency division ratio	2.7 to 3.6		1.1	2.0	
	IDDHALT(8)	1.8 to 5.5		23	260			
			oscillation. Internal medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		13	119	
	IDDHALT(9)		HALT mode External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC	5.0		23	65	
			oscillation. • Internal medium speed RC oscillation stopped.	3.3		13	35	
			Frequency variable RC oscillation stopped. 1/1 frequency division ratio Ta=-10 to +50°C	2.5		9.2	25	
	IDDHALT(10)		HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal low speed and medium speed RC	1.8 to 5.5		25	112	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		8.5	56	
	IDDHALT(11)		HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	5.0		25	69	μА
			Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped.	3.3		8.5	29	μπ
			1/2 frequency division ratio Ta=-10 to +50°C	2.5		4.2	15	
HOLD mode	IDDHOLD(1)		HOLD mode	1.8 to 5.5		0.04	30	
consumption current			CF1=V _{DD} or open (External clock mode)	1.8 to 3.6		0.02	21	
(Note 9-1)	IDDHOLD(2)		HOLD mode	5.0		0.04	2.3	
(Note 9-2)			CF1=V _{DD} or open (External clock mode) Ta=-10 to +50°C	3.3		0.02	1.5	
			14-1010 +50 0	2.5		0.017	1.2	
	IDDHOLD(3)		HOLD mode	1.8 to 5.5		3.2	35	
			CF1=V _{DD} or open (External clock mode) LVD option selected	1.8 to 3.6		2.7	24	
	IDDHOLD(4)		HOLD mode	5.0		3.2	6.5	
			CF1=V _{DD} or open (External clock mode) Ta=-10 to +50°C	3.3		2.7	4.5	
			LVD option selected	2.5		2.5	4.2	
Timer HOLD	IDDHOLD(5)		Timer HOLD mode	1.8 to 5.5		22	106	
mode			FsX'tal=32.768 kHz crystal oscillation mode	1.8 to 3.6		7.5	45	
consumption	IDDHOLD(6)		Timer HOLD mode	5.0		22	62	
current (Note 9-1)			FsX'tal=32.768kHz crystal oscillation mode	3.3		7.5	23	
(Note 9-2)			• Ta=-10 to +50°C	2.5		2.9	12	
-								

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = 0V$

Parameter	Symbol Pin/Remarks		O a maliki a ma		Specification				
Parameter			Conditions	V _{DD} [V]	min	typ	max	unit	
Onboard	IDDFW(1)	V _{DD} 1	Only current of the Flash block.						
programming				2.2 to 5.5		5	10	mA	
current									
Programming	tFW(1)		Erasing time	0.04- 5.5		20	30	ms	
time	tFW(2)		Programming time	2.2 to 5.5		40	60	μs	

UART (Full Duplex) Operating Conditions at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

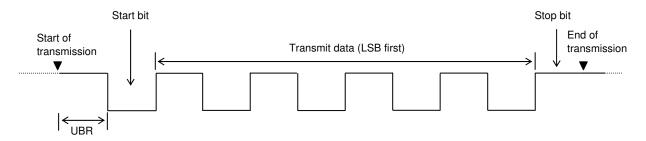
Dawa wa atau	O. made ad	Dia/Damada	O and distance			Specific	cation	
Parameter Symbol Pin/Remarks Condition		Conditions	V _{DD} [V]	min	typ	max	unit	
Transfer rate	UBR	UTX(P20) URX(P21)		1.8 to 5.5	16/3		8192/3	tCYC

Data length: 7/8/9 bits (LSB first)

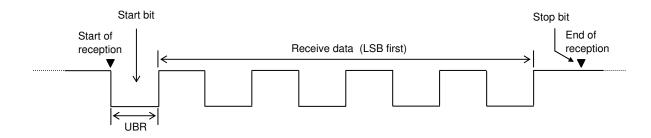
Stop bits: 1 bit (2-bit in continuous data transmission)

Parity bits: None

Example of Continuous 8-bit Data Transmission Mode Processing (First Transmit Data=55H)



Example of Continuous 8-bit Data Reception Mode Processing (First Receive Data=55H)



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

• CF oscillation normal amplifier size selected (CFLAMP=0)

■MURATA

Nominal	_		Circuit Constant				Operating		llation tion Time	D	
Frequency	Frequency	Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks	
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	1.0k	2.7 to 5.5	0.1	0.5		
			(10)	(40)	Open	680	2.2 to 3.6	0.1	0.5		
10MHz	SMD	CSTCE10M0G52-R0	(10)	0) (10)	Open	1.0k	2.3 to 5.5	0.1	0.5		
	LEAD	CSTLS10M0G53-B0	(15)	(15)	Open	1.0k	2.5 to 5.5	0.1	0.5		
	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	1.5k	2.2 to 5.5	0.1	0.5		
8MHz	LEAD	COTI COMOCCEO DO	(15)	(1E)	Open	1.0k	2.2 to 3.6	0.1	0.5	Internal C1, C2	
	LEAD	CSTLS8M00G53-B0		(15)	Open	1.5k	2.4 to 5.5	0.1	0.5	internal C1, C2	
CMILL	SMD	CSTCR6M00G53-R0	(15)	(15)	Open	2.2k	2.2 to 5.5	0.1	0.5		
6MHz	LEAD	CSTLS6M00G53-B0	(15)	(15)	Open	2.2k	2.2 to 5.5	0.1	0.5		
	SMD	CSTCR4M00G53-R0	(15)	(15) (15)	Open	1.5k	1.8 to 2.7	0.2	0.6		
4MHz	SIVID	G31GH4W00G53-R0	(15)		Open	3.3k	1.9 to 5.5	0.2	0.6		
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	3.3k	1.9 to 5.5	0.2	0.6		

• CF oscillation low amplifier size selected (CFLAMP=1)

■MURATA

Nominal Time	T	Oppillator Name		Circuit (Constant		Operating Voltage	Oscillation Stabilization Time		Remarks	
Frequency Type		Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Range [V]	typ [ms]	max [ms]	nemarks	
		00700 4400050 00		(45)	Open	1.0k	2.3 to 2.7	0.2	0.6		
	SMD	CSTCR4M00G53-R0	(15)	15) (15)	Open	2.2k	2.5 to 5.5	0.2	0.6		
4MHz		CSTCR4M00G53095-R0	(15)	(15)	Open	1.0k	2.1 to 2.7	0.2	0.7	Internal	
4IVITZ		COTI CAMOOOFO DO	(15)	(4.5)	Open	1.0k	2.3 to 2.7	0.2	0.6	C1,C2	
LE	LEAD	AD CSTLS4M00G53-B0		(15)	Open	2.2k	2.5 to 5.5	0.2	0.6		
		CSTLS4M00G53095-B0	(15)	(15)	Open	1.0k	2.1 to 2.7	0.2	0.7		

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 3).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

■EPSON TOYOCOM

Nominal	_	Oscillator		Circuit (Constant		Operating Voltage	Oscillation Stabilization Time		
Frequency	Туре	Name	C1	C2	Rf	Rd	Range	typ	max	Remarks
			[pF]	[pF]	$[\Omega]$	$[\Omega]$	[V]	[s]	[s]	
										Applicable
32.768kHz	SMD	MC-306	9	9	Open	330k	1.8 to 5.5	1.4	4.0	CL value =
										7.0pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 3).

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

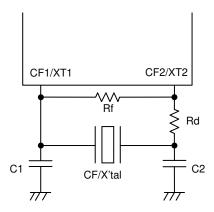


Figure 1 CF and XT Oscillator Circuit

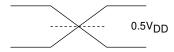


Figure 2 AC Timing Measurement Point